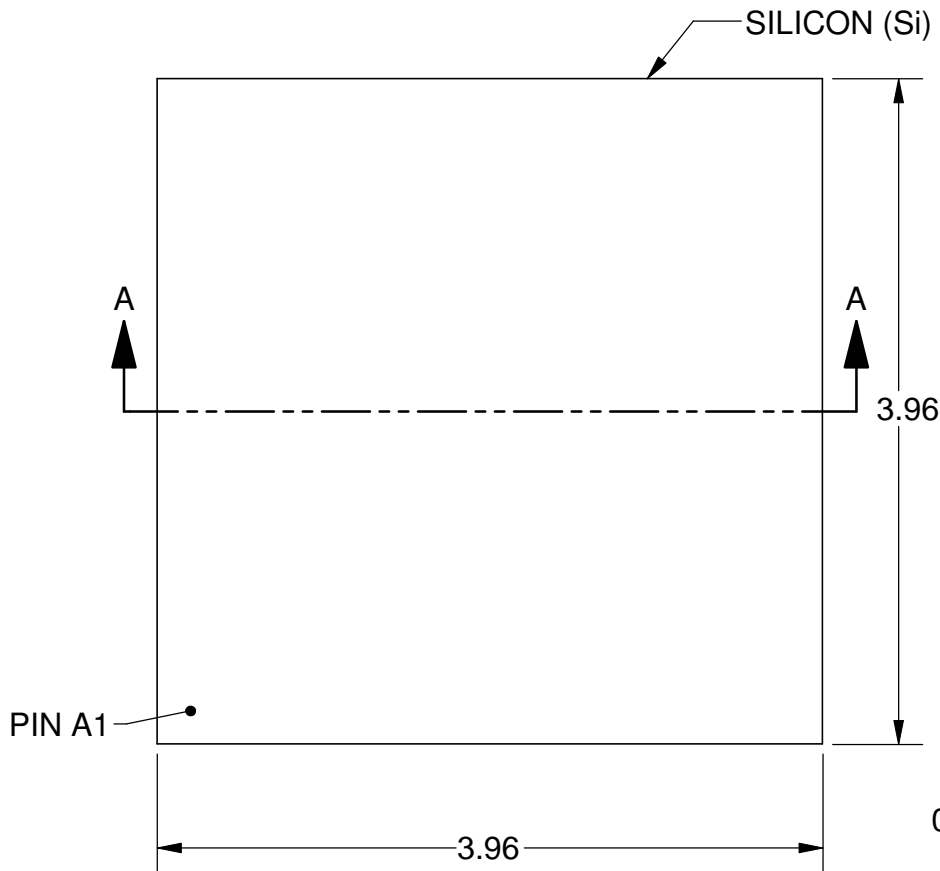
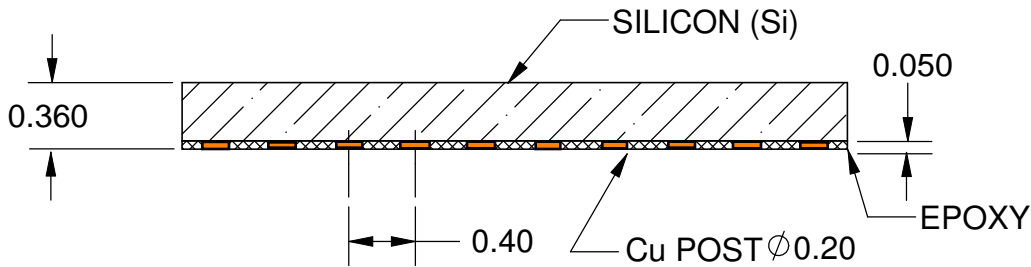
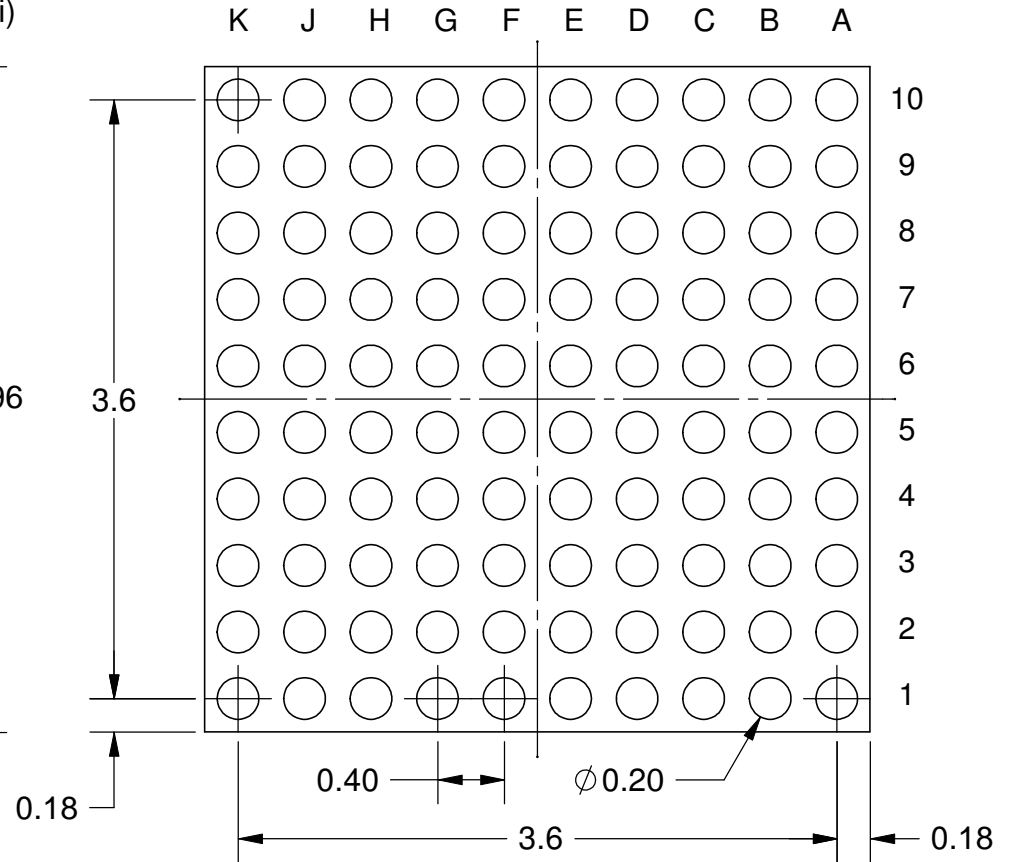


TOP VIEW




PAD VIEW



SECTION A-A

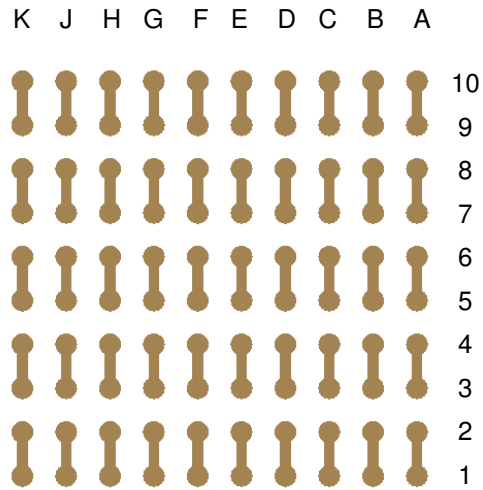
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) PAD ALLOY: Cu Post (50um Thick)
- 3) PAD Cu DIAMETER: 0.20mm.
- 4) DIE MATERIAL: Si (SILICON).
- 5) DAISY CHAIN PATTERN (SEE PAGE 2).

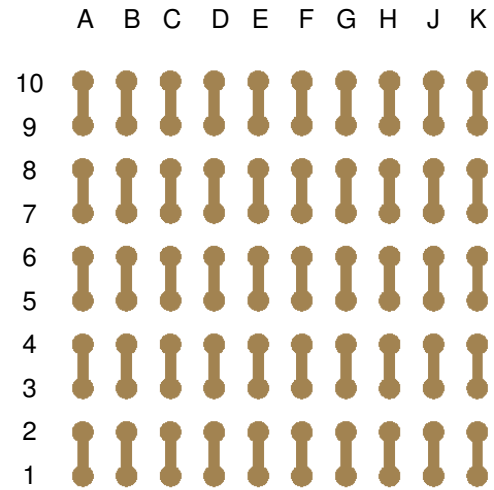
TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.X	+/- 0.3						
X.XX	+/- 0.03	DRAWN J. Hines	12/30/2010	TITLE eWLP100T.4-DC108D3 100-L P=0.4mm (TEG0408)			
X.XXX	+/- 0.003						
ANGLES	+/- 0.5°	ENG		SCALE 22:1 SIZE A DRAWING NO. 741080 REV A			
ALL DIMENSIONS IN		MFG					
<input type="checkbox"/> INCHES	<input checked="" type="checkbox"/> MILLIMETERS	QA		DO NOT SCALE DRAWING SHEET 1 OF 2			
THIRD ANGLE PROJECTION		CUST					
		REVISED					

DAISY CHAIN PATTERN

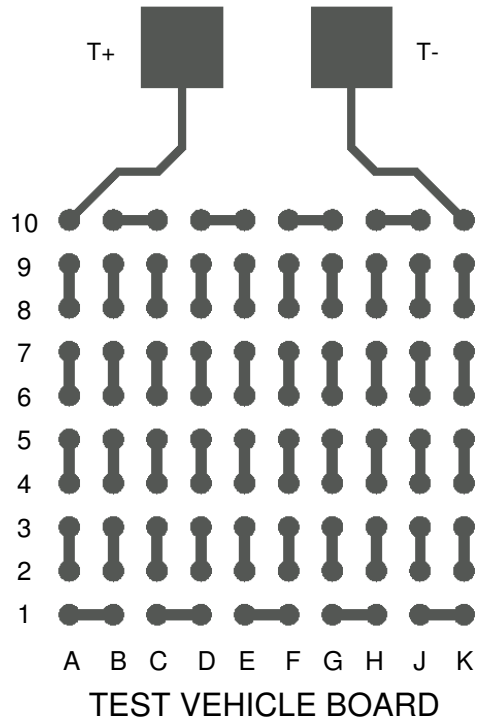
PAD VIEW



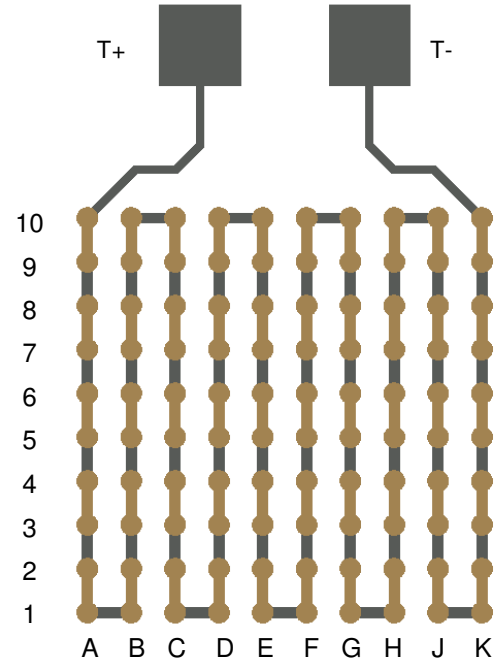
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP100T.4-DC108D3 100-PAD P=0.4mm (TEG0408)			
SCALE 14.5:1	SIZE A	DRAWING NO. 741080	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	